

FIG. 1

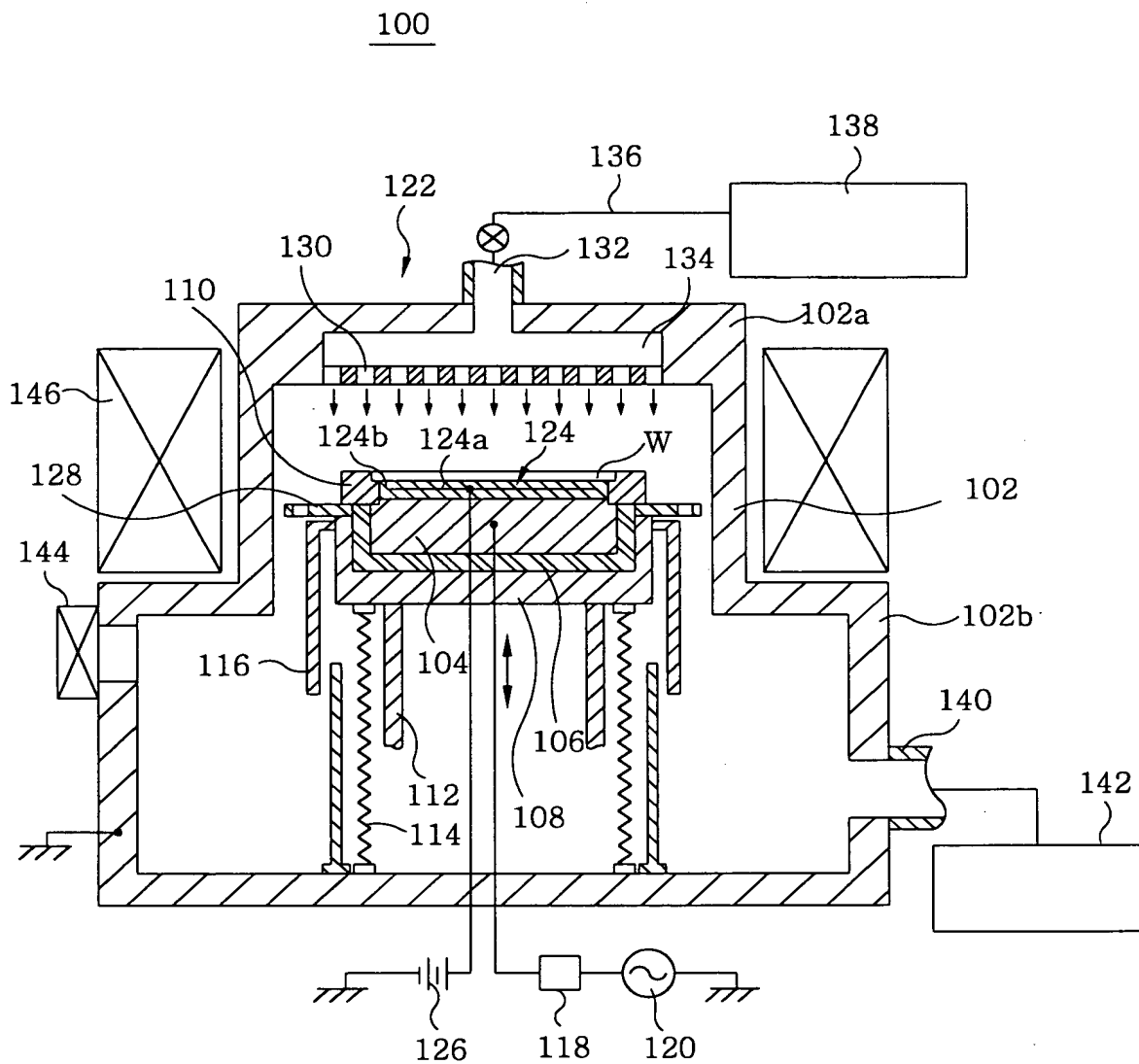


FIG.2A

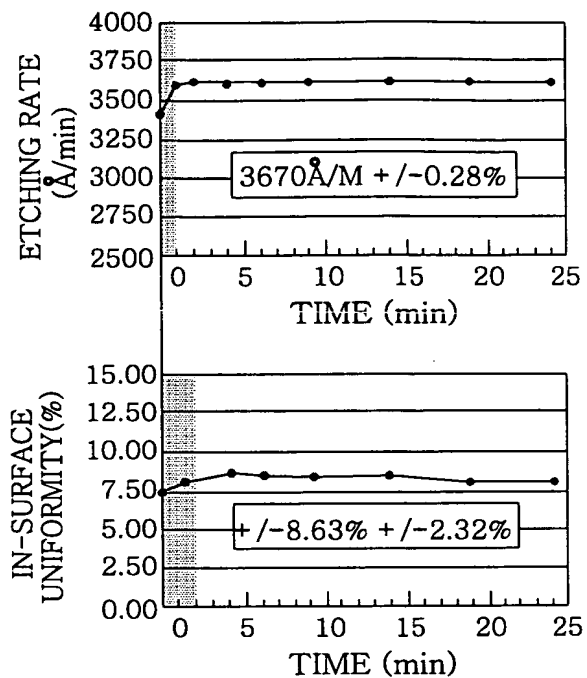


FIG.2B

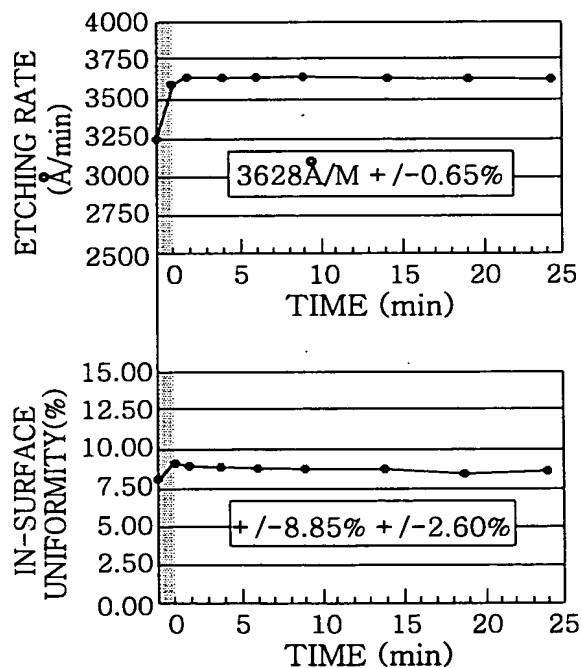


FIG.2C

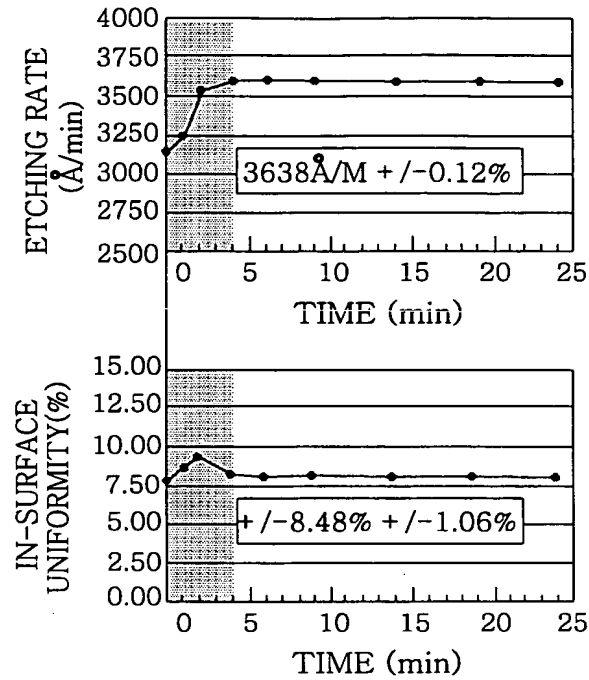


FIG.2D

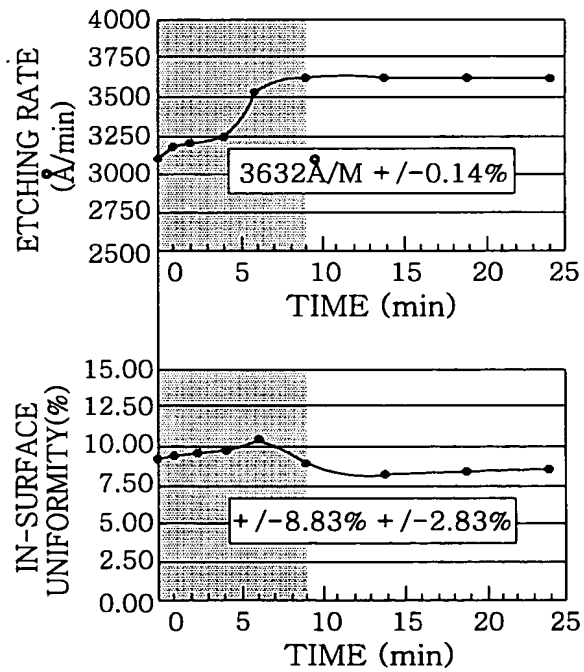


FIG. 3

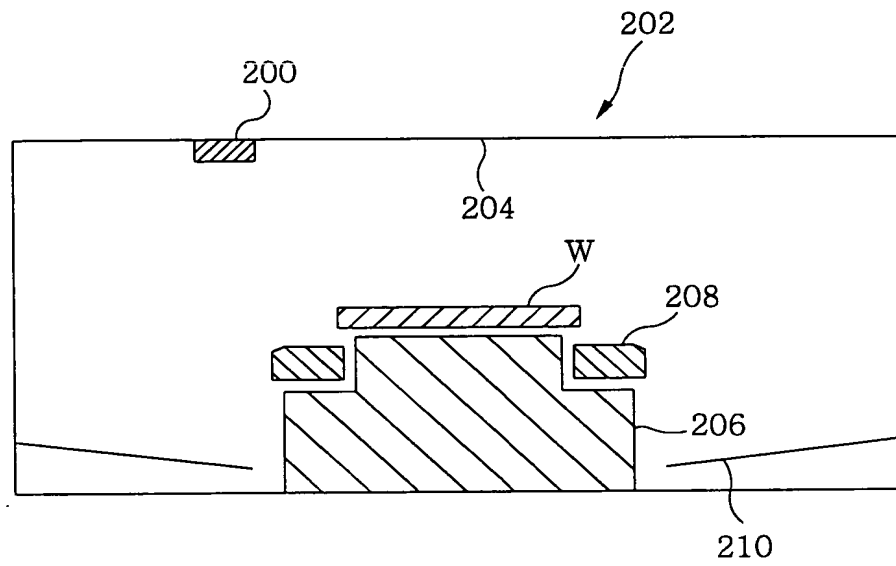


FIG. 4

XPS ANALYSIS RESULT OF
SURFACE OF Y_2O_3 CHIP

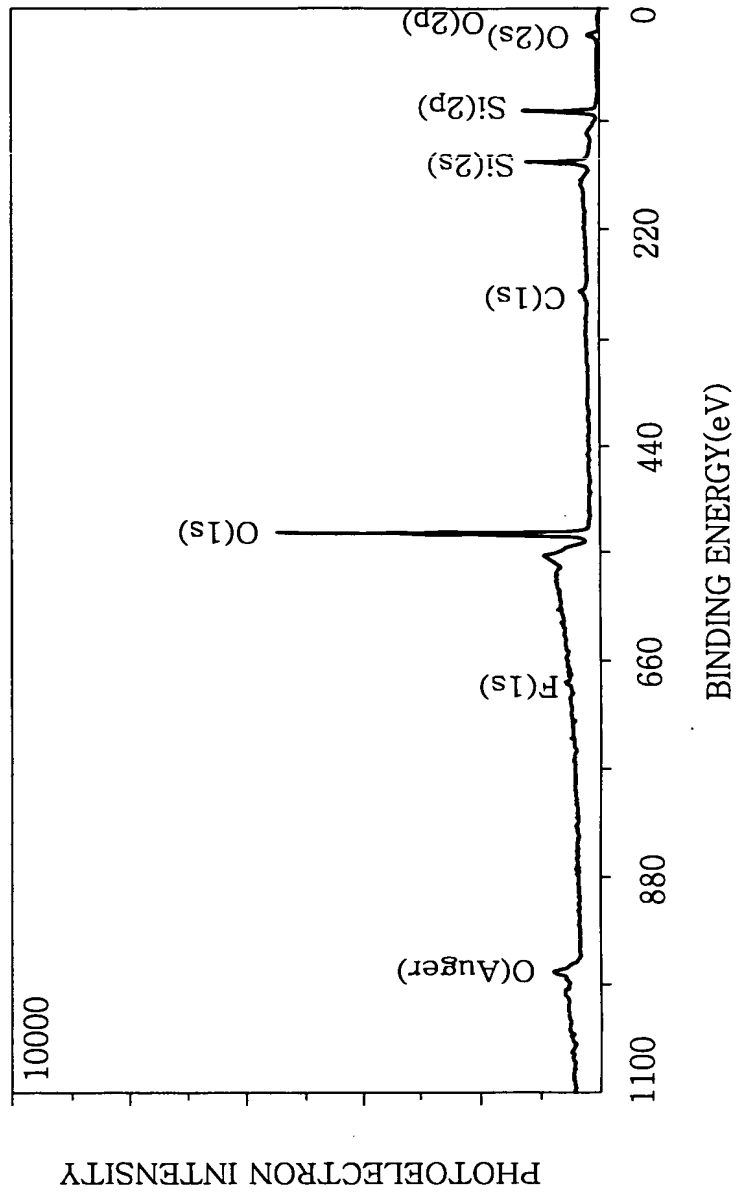


FIG.5

XPS ANALYSIS RESULT OF
SURFACE OF Y_2O_3 CHIP

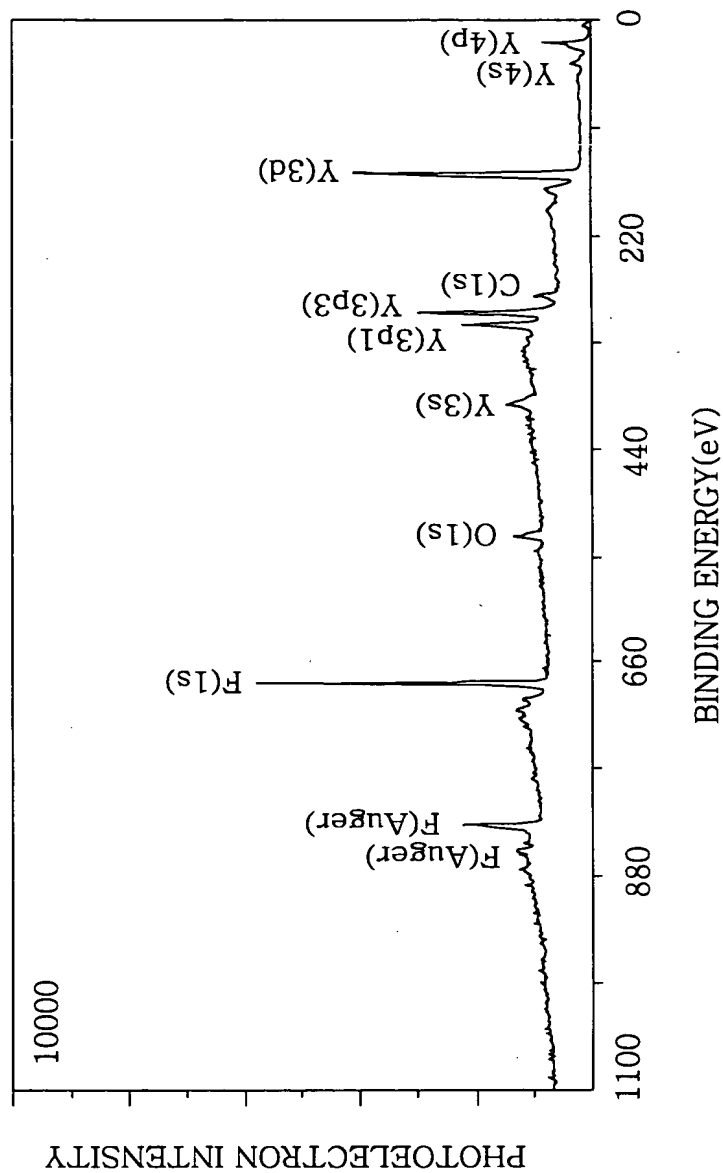


FIG.6

XPS ANALYSIS RESULT OF
SURFACE OF Y_2O_3 CHIP

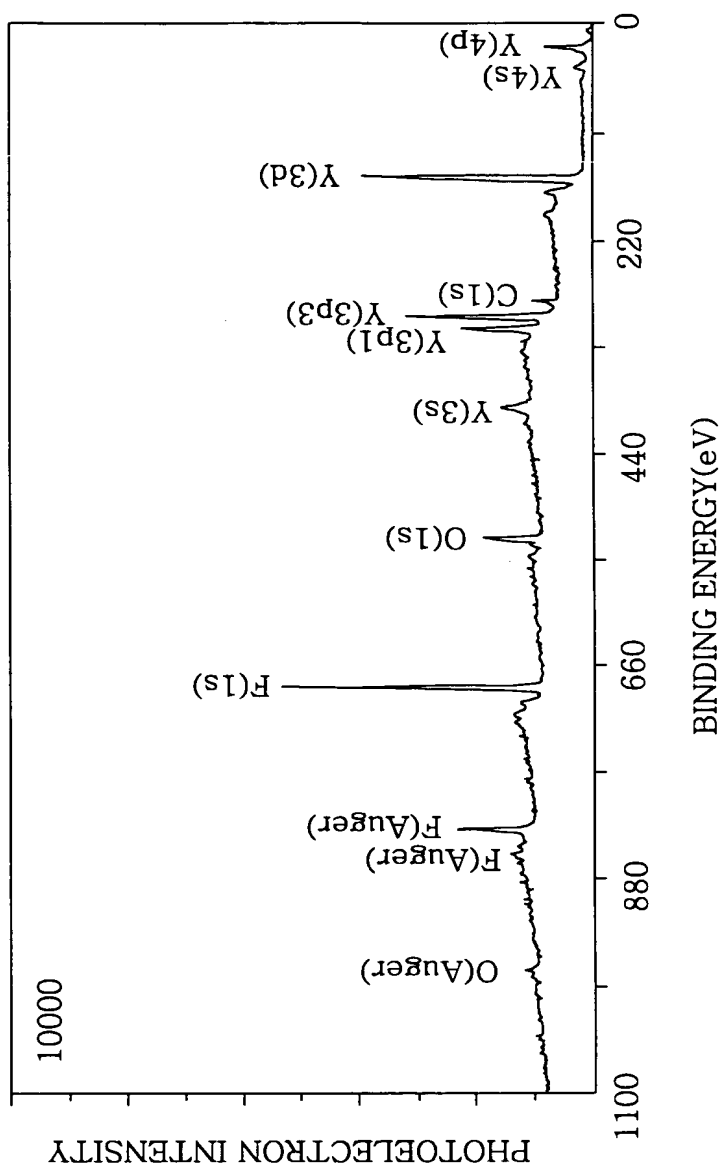


FIG. 7A

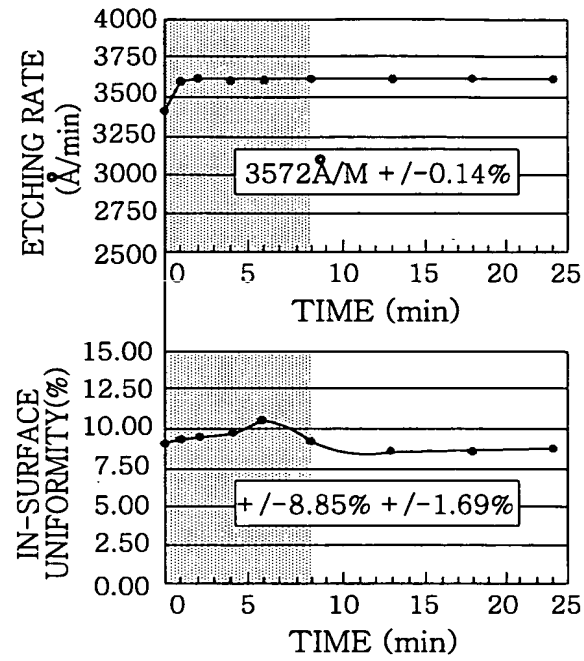


FIG. 7B

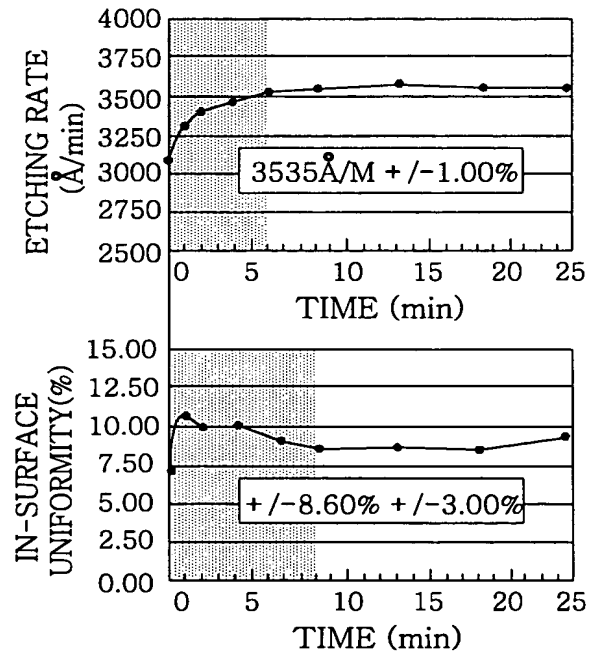


FIG. 7C

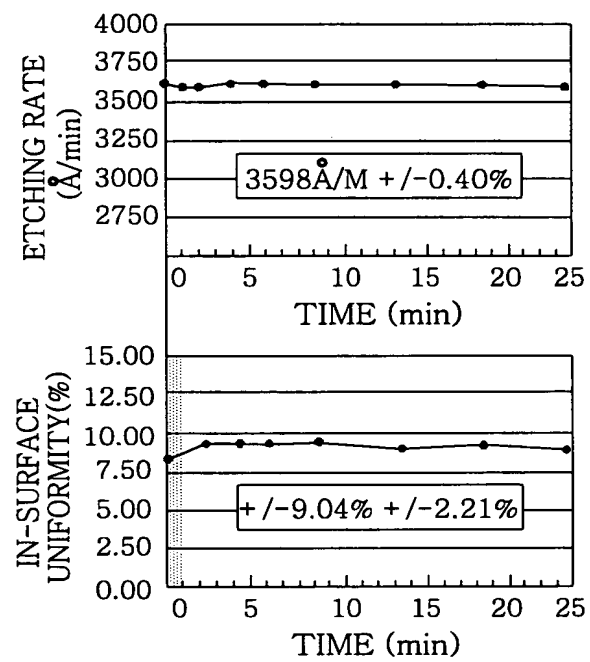


FIG. 8A

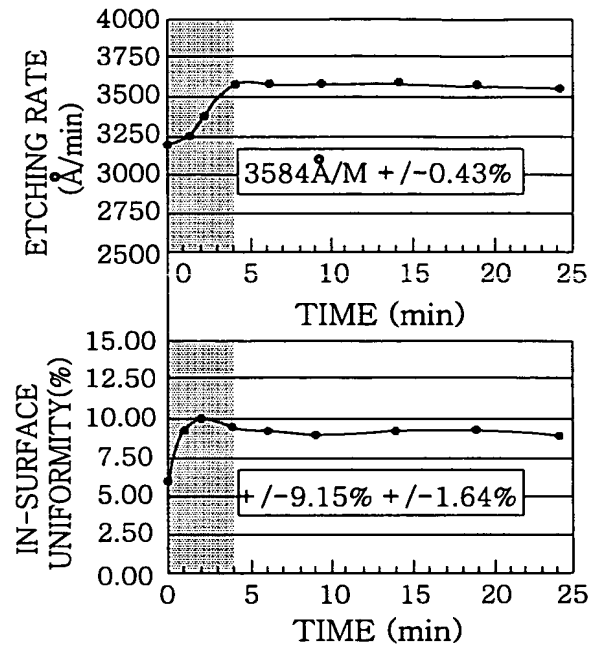


FIG. 8B

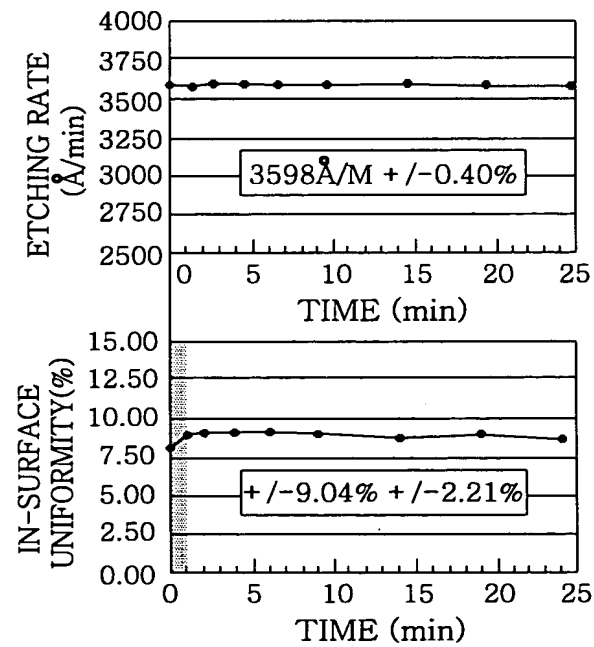


FIG. 8C

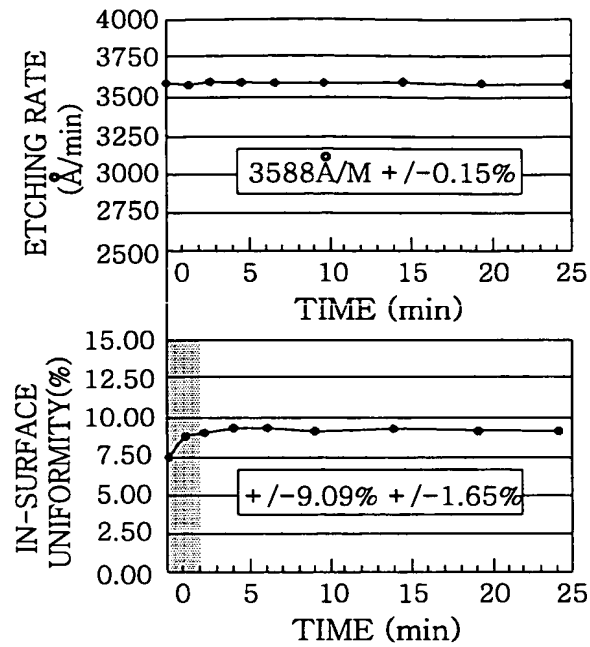


FIG. 8D

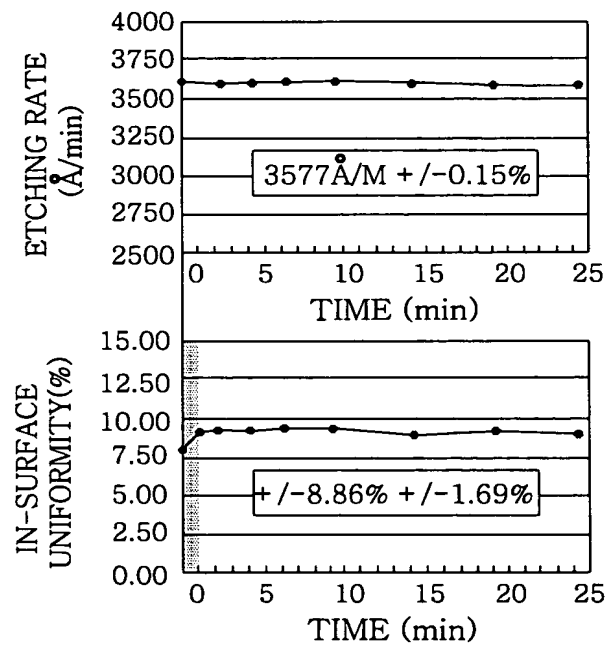


FIG. 9

300

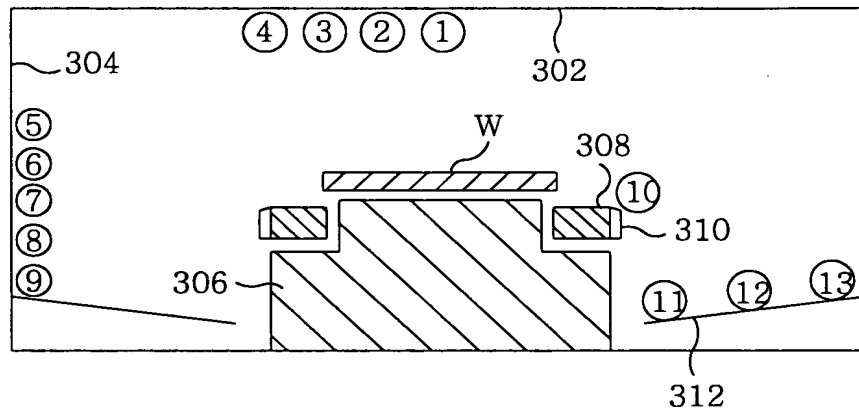


FIG. 10

CF ₄ FLOW RATE	ASHING RATE (Å/min)	
	0 sccm	2 sccm
① CEILING PLATE 0mm(Center)	7877	7598
② CEILING PLATE 50mm	8398	7976
③ CEILING PLATE 95mm	9304	9136
④ CEILING PLATE 140mm(Edge)	8994	9387
⑤ DEPOSITION SHIELD 50mm(Top)	8674	7615
⑥ DEPOSITION SHIELD 40mm	10540	9896
⑦ DEPOSITION SHIELD 30mm	8849	8285
⑧ DEPOSITION SHIELD 20mm	10323	9696
⑨ DEPOSITION SHIELD 10mm(Bot)	12260	11907
⑩ INSULATOR RING	18295	17513
⑪ BAFFLE PLATE Center	9524	9016
⑫ BAFFLE PLATE Middle	12012	11701
⑬ BAFFLE PLATE Edge	12152	11504
Max.	18295	17513
Min.	7877	7598
Ave.	10554	10095
Unif.	49.36	49.11

FIG. 11

APPLIED POWER	TIME REQUIRED TO REMOVE THE DEPOSIT (s)		
	500 W	1000 W	1500 W
① CEILING PLATE 0mm(Center)	551	351	254
② CEILING PLATE 50mm	590	361	283
③ CEILING PLATE 95mm	518	363	298
④ CEILING PLATE 140mm(Edge)	312	257	234
⑤ DEPOSITION SHIELD 50mm(Top)	0	0	0
⑥ DEPOSITION SHIELD 40mm	0	0	0
⑦ DEPOSITION SHIELD 30mm	26	20	17
⑧ DEPOSITION SHIELD 20mm	146	113	95
⑨ DEPOSITION SHIELD 10mm(Bot)	243	167	140
⑩ INSULATOR RING	0	0	0
⑪ BAFFLE PLATE Center	0	0	0
⑫ BAFFLE PLATE Middle	184	120	102
⑬ BAFFLE PLATE Edge	434	270	222
Max.	590	363	298
Min.	0	0	0
Ave.	231	156	127
Unif.	127.68	116.68	117.92

FIG. 12A



FIG. 12B
(PRIOR ART)

